

RoHS Compliant Product  
A Suffix of "-C" specifies halogen & lead-free

## DESCRIPTIONS

The SMS123-C is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge.

This device is suitable for use in DC-DC conversion, load switch and level shift.

## MECHANICAL DATA

- Trench Technology
- Supper High Density Cell Design
- Excellent On Resistance
- Extremely Low Threshold Voltage

## APPLICATION

- DC-DC Converter Circuit
- Load Switch

## MARKING

**B123**

## PACKAGE INFORMATION

Package	MPQ	Leader Size
SOT-23	3K	7 inch

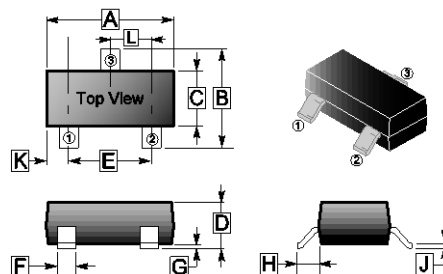
## ORDER INFORMATION

Part Number	Type
SMS123-C	Lead (Pb)-free and Halogen-free

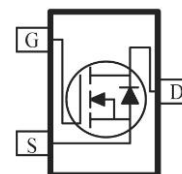
## MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D$	0.17	A
Pulsed Drain Current @ $t_p=10\mu\text{s}$	$I_{DM}$	0.68	A
Continuous Source-Drain Diode Current	$I_S$	0.17	A
Power Dissipation	$P_D$	0.35	W
Thermal Resistance from Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	357	$^{\circ}\text{C/W}$
Lead Temperature for Soldering Purposes (1/8" from case for 10s)	$T_L$	260	$^{\circ}\text{C}$
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	150, -55~150	$^{\circ}\text{C}$

### SOT-23



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.65	3.10	G	-	0.18
B	2.10	3.00	H	0.55	REF.
C	1.10	1.80	J	0.05	0.26
D	0.89	1.40	K	0.60	REF.
E	1.70	2.30	L	0.95	TYP.
F	0.28	0.55			



**ELECTRICAL CHARACTERISTICS** (T<sub>A</sub>=25°C unless otherwise specified)

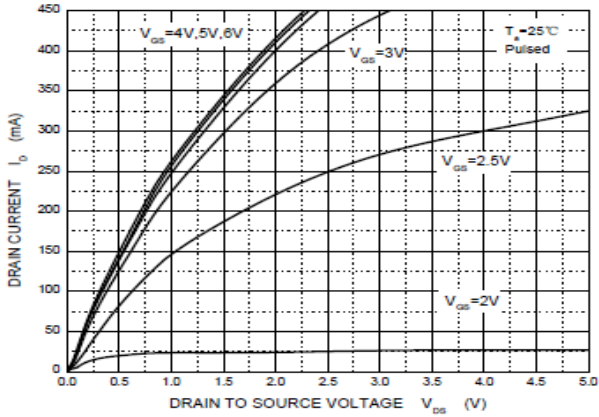
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	100	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V
		-	-	10	nA	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V
Gate-Source Leakage	I <sub>GSS</sub>	-	-	10	μA	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V
Gate-Threshold Voltage <sup>2</sup>	V <sub>GS(th)</sub>	1	1.6	2.8	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
Drain-Source On Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	-	-	6	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =0.17A
		-	-	10		V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.17A
Forward Transfer conductance <sup>2</sup>	g <sub>fs</sub>	80	-	-	mS	V <sub>DS</sub> =10V, I <sub>D</sub> = 0.17A
<b>Body-Drain Diode Ratings</b>						
Diode Forward On-Voltage	V <sub>SD</sub>	-	-	1.3	V	I <sub>S</sub> =340mA, V <sub>GS</sub> =0V
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	-	45	80	pF	V <sub>DS</sub> =25V V <sub>GS</sub> =0V f=1MHz
Output Capacitance	C <sub>oss</sub>	-	11	25		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	1	6		
<b>Switching Characteristics <sup>3</sup></b>						
Total Gate Charge	Q <sub>g</sub>	-	1.75	-	nC	V <sub>DS</sub> =10V V <sub>GS</sub> =10V I <sub>D</sub> =0.22A
Gate-Source Charge	Q <sub>gs</sub>	-	0.48	-		
Gate-Drain Charge	Q <sub>gd</sub>	-	0.16	-		
Turn-on Delay Time	T <sub>d(on)</sub>	-	3.3	-	nS	V <sub>DD</sub> =30V I <sub>D</sub> =0.28A V <sub>GS</sub> =10V R <sub>GEN</sub> =50Ω
Rise Time	T <sub>r</sub>	-	3.3	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	12.9	-		
Fall Time	T <sub>f</sub>	-	39.4	-		

Notes:

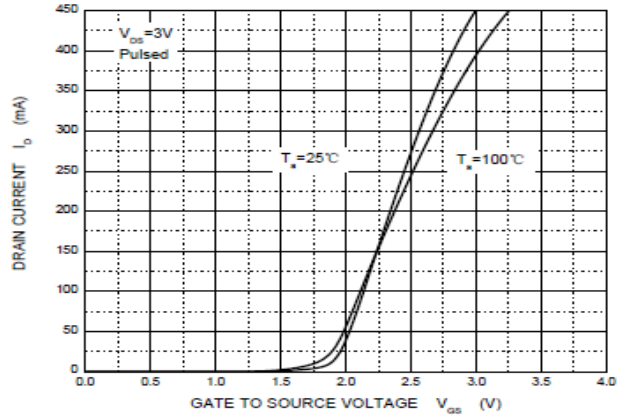
- Surface mounted on FR-4 Board using the minimum recommended pad size.
- Pulse Test: Pulse width=300μs, duty cycle ≤2%.
- Switching characteristics are independent of operating junction temperature.

**CHARACTERISTIC CURVES**

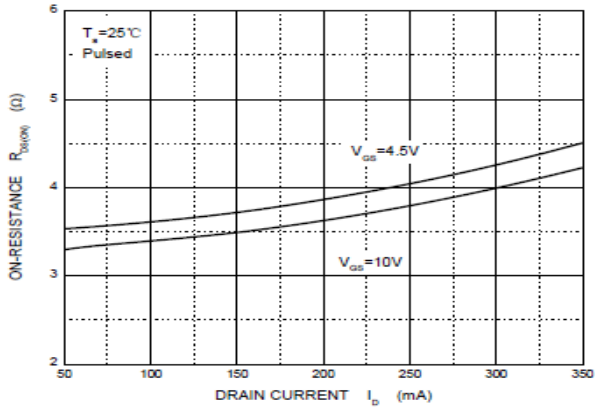
Output Characteristics



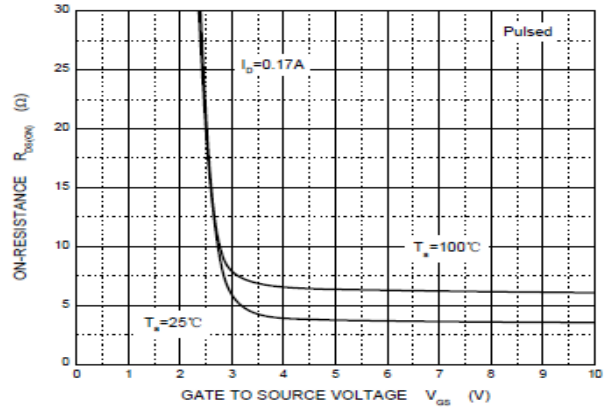
Transfer Characteristics



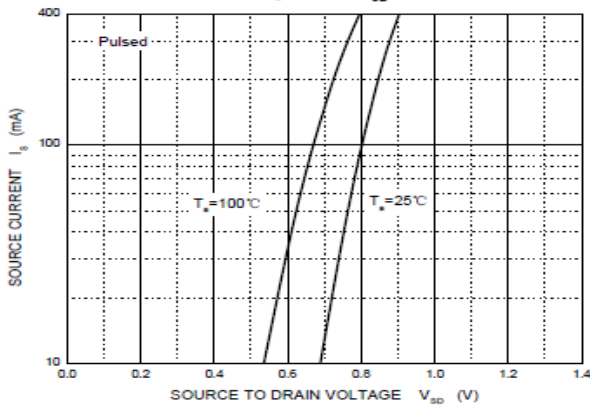
$R_{DS(ON)}$  —  $I_D$



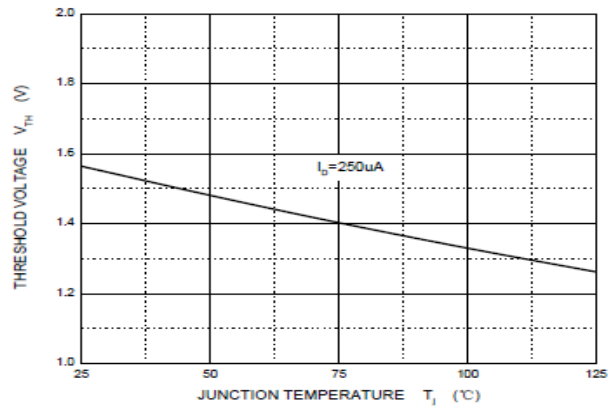
$R_{DS(ON)}$  —  $V_{GS}$



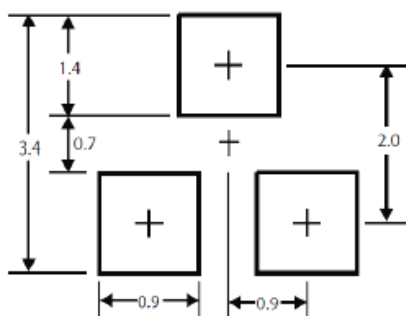
$I_S$  —  $V_{SD}$



Threshold Voltage



Mounting Pad Layout



\*Dimensions in millimeters